

SOLDER PASTE

LEAD-FREE HIGH TEMPERATURE SOLDER PASTE



Sn99/Ag0.3/Cu0.7

Melting point 217°C



Product Usage



TIN PASTE

| | |
|----------------------|---|
| Model | BST-705A |
| Name | Lead-free high temperature solder paste |
| Composition | Sn99/Ag0.3/Cu0.7 |
| Melting point | 217°C |
| G.W. | 50g |
| Granule | 20~38μm |
| Size | φ50*16mm |

Sn99/Ag0.3/Cu0.7

Lead-free high temperature melting point

217°C





Low residue

Fine grain

Rapid welding

Solder spot bright

Welding requirements for a wide range of products



SMT
patch



LED
patch



BGA
welding

Product Size



G.W.:50g

